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(54) **Title:** ELECTRONIC DEVICE COOLING MODULE

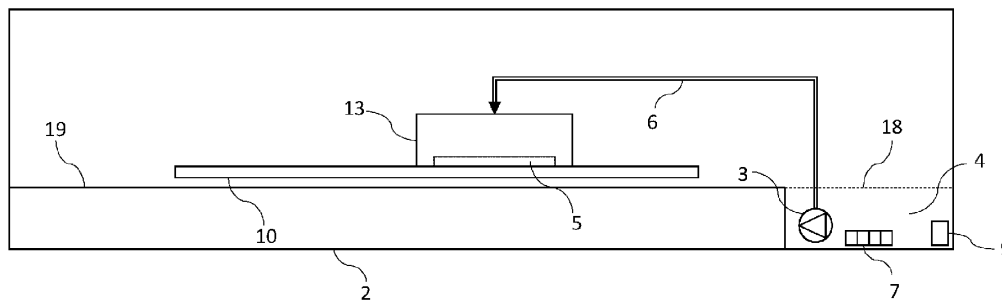


Fig. 2.

(57) **Abstract:** An electronic device cooling module (1) comprises: a container (2) enclosing at least one first electronic device (5); a liquid coolant reservoir (4); and a pump (3) located within the liquid coolant reservoir (4) arranged to pump liquid coolant from said liquid coolant reservoir (4) to the at least one first electronic device (5) via a liquid coolant conduit (6) to provide cooling of the device. The liquid coolant reservoir (4) includes a heating element (7) communicably coupled to a controller (8). The controller (8) is communicably coupled to a temperature sensor (9) disposed within the liquid coolant reservoir (4).



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